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FACSIMILE COVER SHEET

To: T. Dinh
Art Unit 2827

From: Daniel J. Bedell

Firm: US PATENT AND
TRADEMARK OFFICE

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#6 Response
Hayes
PATENT
9/5/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Charles A. MILLER

Art Unit: 2827

Application No: 09/970,749

Examiner:
T. Dinh

Filed: October 3, 2001

For: MULTIPLE DIE INTERCONNECT SYSTEM

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REPLY TO THE OFFICE ACTION MAILED 04/25/2002

AUG 26 2002

Assistant Commissioner for Patents
Washington, D.C. 20231

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Sir:

Further examination and consideration of this application are requested in view of the following Remarks.

REMARKS

The following numbered sections of these remarks respond to similarly numbered sections of the office action.

2,3 Claims 21-24 and 29-30 are rejected under 35 U.S.C. 102(b) as being anticipated by U.S. patent 5,569,952 (HAYASHI). The Examiner is respectfully requested to withdraw the rejection of claims 21-24 and 29-30 in view of the comments below distinguishing the applicant's claims over HAYASHI.

Claim 21

Claim 21 is patentable over HAYASHI because HAYASHI fails to disclose the "base IC die", the "first secondary IC die", or the "conductive contacts" as recited in claim 1,

The Examiner errs in pointing to item 2 of HAYASHI's FIG. 3 as being a "base IC die" as recited in claim 1. Item 2 is a circuit board, not an IC die. See HAYASHI, column 4, lines 46- 47.

The Examiner errs in pointing to item 3 of HAYASHI's FIG. 3 as being "a first secondary IC die ... linked to the first surface of the base IC die through first conductive signal paths" as recited in claim